

HD74LS04 / HD74LS05

Hex Inverters / Hex Inverters (with Open Collector Outputs)

REJ03D0391-0300
Rev.3.00
Jul.13.2005

Features

- Ordering Information

• HD74LS04

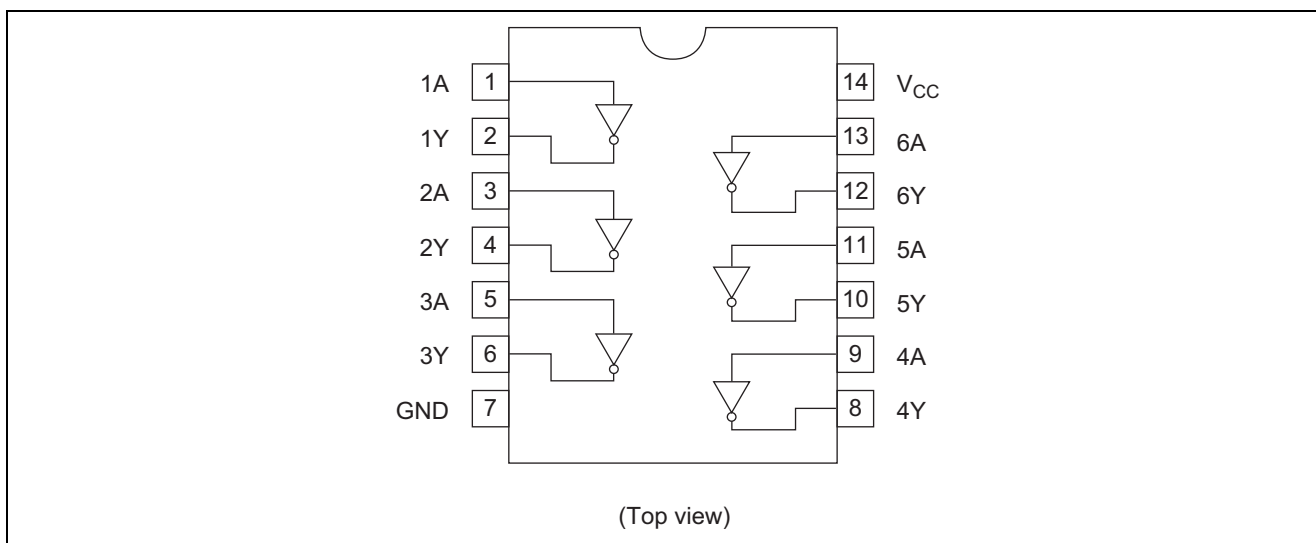
Part Name	Package Type	Package Code (Previous Code)	Package Abbreviation	Taping Abbreviation (Quantity)
HD74LS04P	DILP-14 pin	PRDP0014AB-B (DP-14AV)	P	—
HD74LS04FPEL	SOP-14 pin (JEITA)	PRSP0014DF-B (FP-14DAV)	FP	EL (2,000 pcs/reel)
HD74LS04RPEL	SOP-14 pin (JEDEC)	PRSP0014DE-A (FP-14DNV)	RP	EL (2,500 pcs/reel)

• HD74LS05

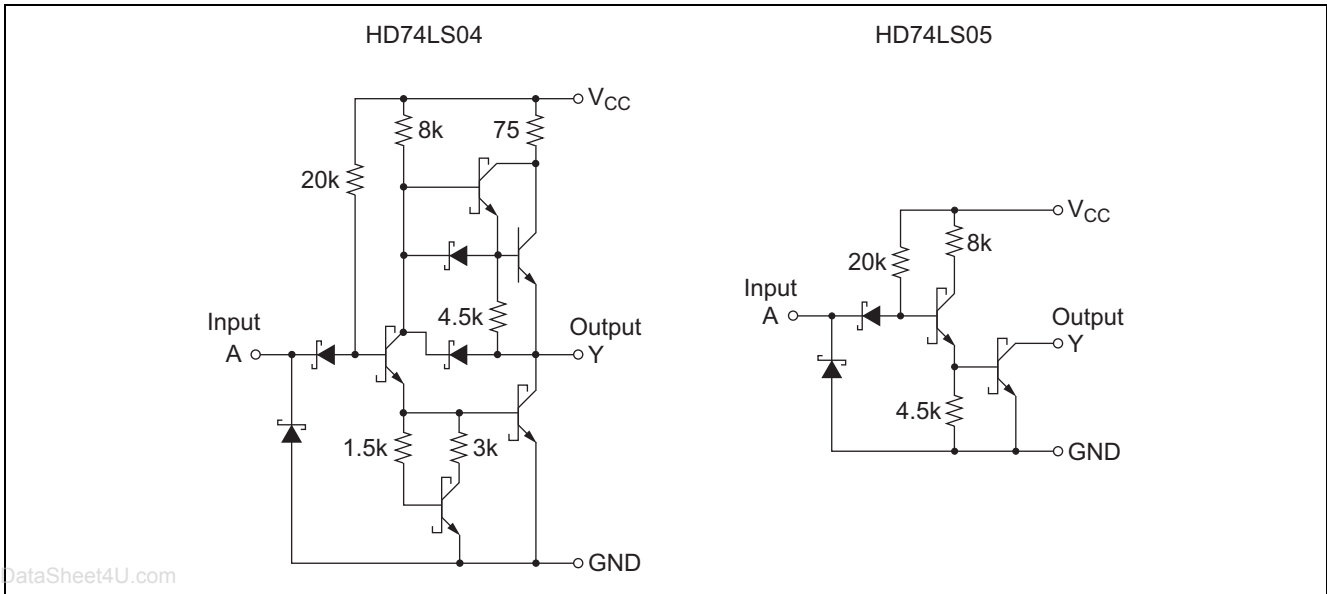
Part Name	Package Type	Package Code (Previous Code)	Package Abbreviation	Taping Abbreviation (Quantity)
HD74LS05P	DILP-14 pin	PRDP0014AB-B (DP-14AV)	P	—
HD74LS05FPEL	SOP-14 pin (JEITA)	PRSP0014DF-B (FP-14DAV)	FP	EL (2,000 pcs/reel)
HD74LS05RPEL	SOP-14 pin (JEDEC)	PRSP0014DE-A (FP-14DNV)	RP	EL (2,500 pcs/reel)

Note: Please consult the sales office for the above package availability.

Pin Arrangement



Circuit Schematic (1/6)



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Absolute Maximum Ratings

Item	Symbol	Ratings	Unit
Supply voltage	V_{CC} ^{Note}	7	V
Input voltage	V_{IN}	7	V
Power dissipation	P_T	400	mW
Storage temperature	Tstg	-65 to +150	°C

Note: Voltage value, unless otherwise noted, are with respect to network ground terminal.

Recommended Operating Conditions

• HD74LS04

Item	Symbol	Min	Typ	Max	Unit
Supply voltage	V_{CC}	4.75	5.00	5.25	V
Output current	I_{OH}	—	—	-400	μA
	I_{OL}	—	—	8	mA
Operating temperature	T_{opr}	-20	25	75	°C

• HD74LS05

Item	Symbol	Min	Typ	Max	Unit
Supply voltage	V_{CC}	4.75	5.00	5.25	V
Output voltage	V_{OH}	—	—	5.5	V
Output current	I_{OL}	—	—	8	mA
Operating temperature	T_{opr}	-20	25	75	°C

Electrical Characteristics

• **HD74LS04**

(Ta = -20 to +75 °C)

Item	Symbol	min.	typ.*	max.	Unit	Condition
Input voltage	V _{IH}	2.0	—	—	V	
	V _{IL}	—	—	0.8	V	
Output voltage	V _{OH}	2.7	—	—	V	V _{CC} = 4.75 V, V _{IL} = 0.8 V, I _{OH} = -400 μA
	V _{OL}	—	—	0.5	V	V _{CC} = 4.75 V, V _{IH} = 2 V
—		—	0.4			
Input current	I _{IH}	—	—	20	μA	V _{CC} = 5.25 V, V _I = 2.7 V
	I _{IL}	—	—	-0.4	mA	V _{CC} = 5.25 V, V _I = 0.4 V
	I _I	—	—	0.1	mA	V _{CC} = 5.25 V, V _I = 7 V
Short-circuit output current	I _{OS}	-20	—	-100	mA	V _{CC} = 5.25 V
Supply current	I _{CCH}	—	1.2	2.4	mA	V _{CC} = 5.25 V
	I _{CCL}	—	3.6	6.6	mA	V _{CC} = 5.25 V
Input clamp voltage	V _{IK}	—	—	-1.5	V	V _{CC} = 4.75 V, I _{IN} = -18 mA

Note: * V_{CC} = 5 V, Ta = 25°C

• **HD74LS05**

(Ta = -20 to +75 °C)

Item	Symbol	min.	typ.*	max.	Unit	Condition
Input voltage	V _{IH}	2.0	—	—	V	
	V _{IL}	—	—	0.8	V	
Output voltage	V _{OL}	—	—	0.5	V	V _{CC} = 4.75 V, V _{IH} = 2 V
		—	—	0.4		
Output current	I _{OH}	—	—	100	μA	V _{CC} = 4.75 V, V _{IL} = 0.8 V, V _{OA} = 5.5 V
Input current	I _{IH}	—	—	20	μA	V _{CC} = 5.25 V, V _I = 2.7 V
	I _{IL}	—	—	-0.4	mA	V _{CC} = 5.25 V, V _I = 0.4 V
	I _I	—	—	0.1	mA	V _{CC} = 5.25 V, V _I = 7 V
Supply current	I _{CCH}	—	1.2	2.4	mA	V _{CC} = 5.25 V
	I _{CCL}	—	3.6	6.6	mA	V _{CC} = 5.25 V
Input clamp voltage	V _{IK}	—	—	-1.5	V	V _{CC} = 4.75 V, I _{IN} = -18 mA

Note: * V_{CC} = 5 V, Ta = 25°C

Switching Characteristics

• **HD74LS04**

(V_{CC} = 5 V, Ta = 25°C)

Item	Symbol	min.	typ.	max.	Unit	Condition
Propagation delay time	t _{PLH}	—	9	15	ns	C _L = 15 pF, R _L = 2 kΩ
	t _{PHL}	—	10	15	ns	

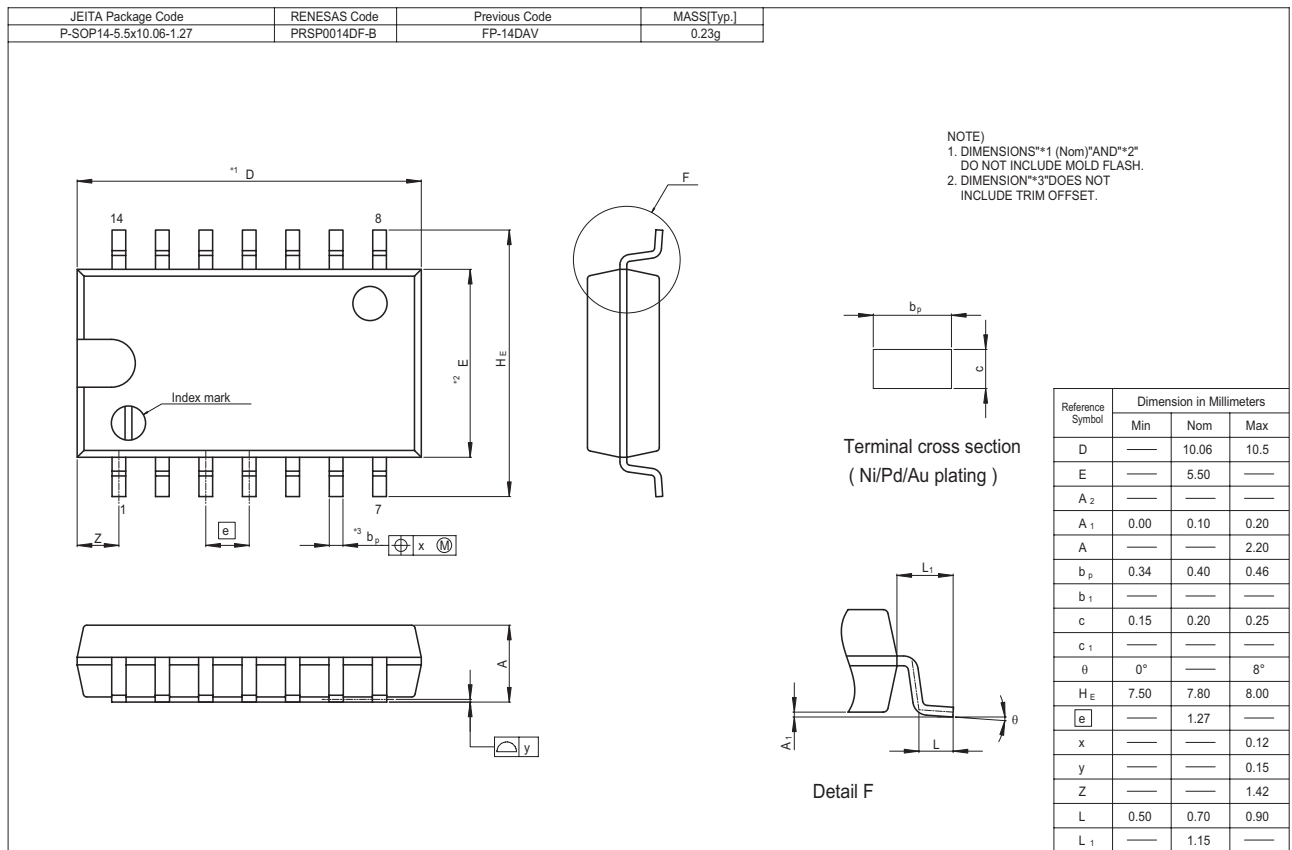
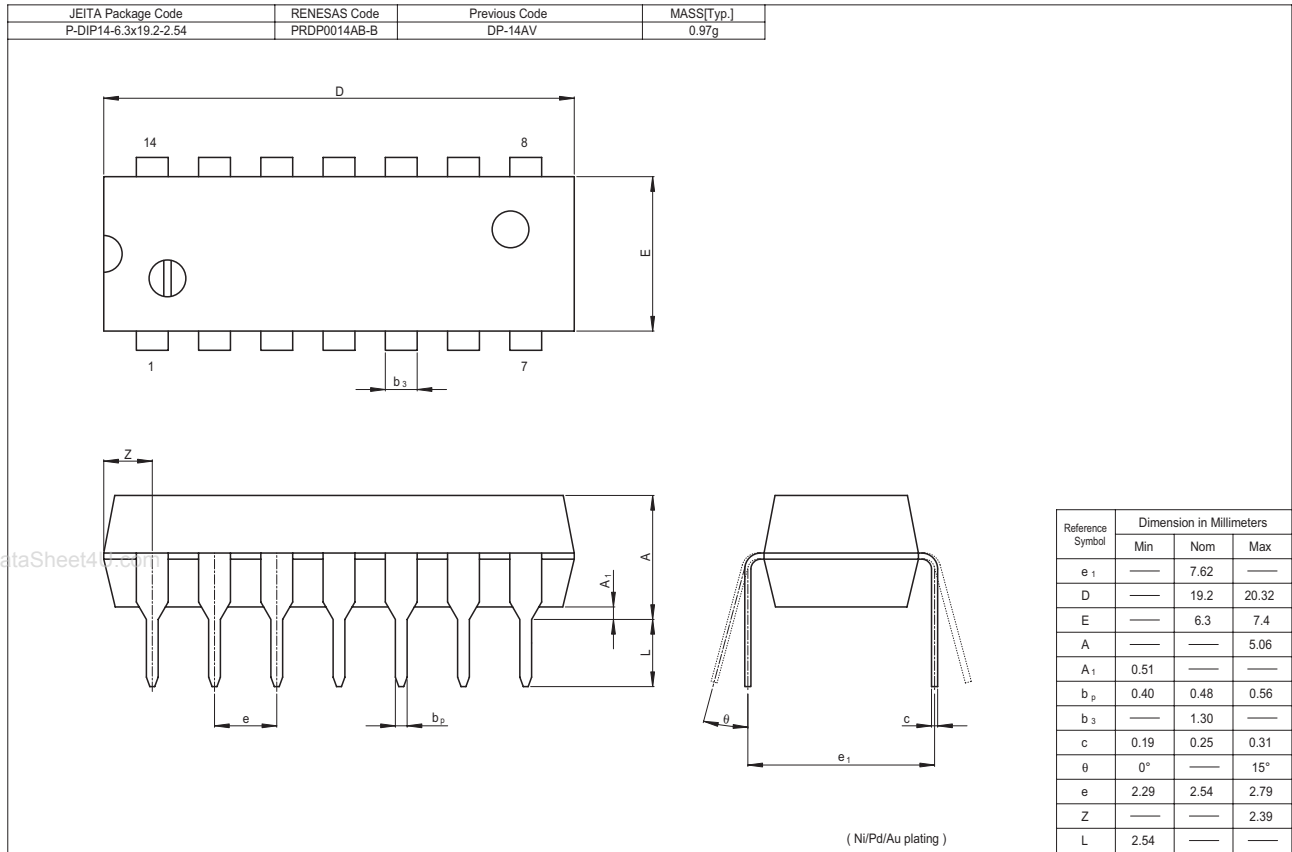
• **HD74LS05**

(V_{CC} = 5 V, Ta = 25°C)

Item	Symbol	min.	typ.	max.	Unit	Condition
Propagation delay time	t _{PLH}	—	17	32	ns	C _L = 15 pF, R _L = 2 kΩ
	t _{PHL}	—	15	28	ns	

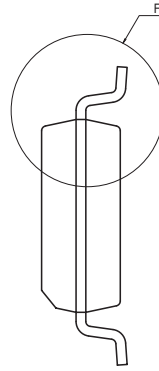
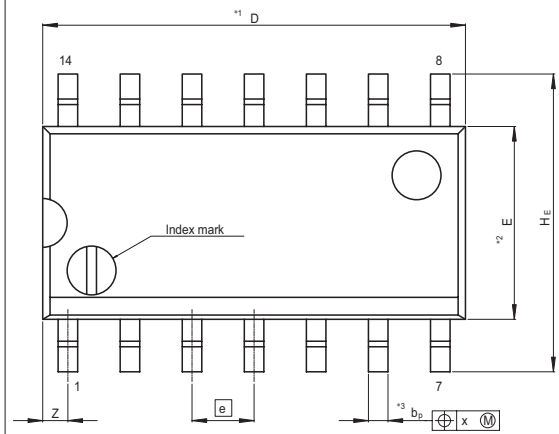
Note: Refer to Test Circuit and Waveform of the Common Item "TTL Common Matter (Document No.: REJ27D0005-0100)".

Package Dimensions

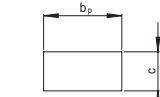


HD74LS04 / HD74LS05

JEITA Package Code P-SOP14-3.95x8.65-1.27	RENESAS Code PRSP0014DE-A	Previous Code FP-14DNV	MASS[Typ.] 0.13g
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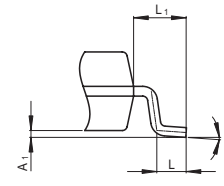
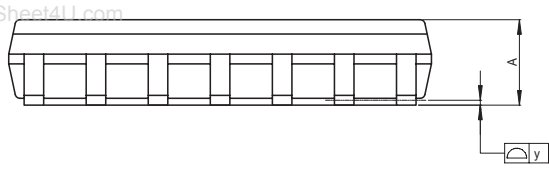


NOTE)
1. DIMENSIONS*1 (Nom)*AND*2*
DO NOT INCLUDE MOLD FLASH.
2. DIMENSION*3*DOES NOT
INCLUDE TRIM OFFSET.



Terminal cross section
(Ni/Pd/Au plating)

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	—	8.65	9.05
E	—	3.95	—
A ₂	—	—	—
A ₁	0.10	0.14	0.25
A	—	—	1.75
b _p	0.34	0.40	0.46
b ₁	—	—	—
c	0.15	0.20	0.25
c ₁	—	—	—
θ	0°	—	8°
H _E	5.80	6.10	6.20
e	—	1.27	—
x	—	—	0.25
y	—	—	0.15
Z	—	—	0.635
L	0.40	0.60	1.27
L ₁	—	1.08	—



Detail F

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